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(54) Title: PROTECTION OF WIRE-BOND BALL GRID ARRAY PACKAGED INTEGRATED CIRCUIT CHIPS

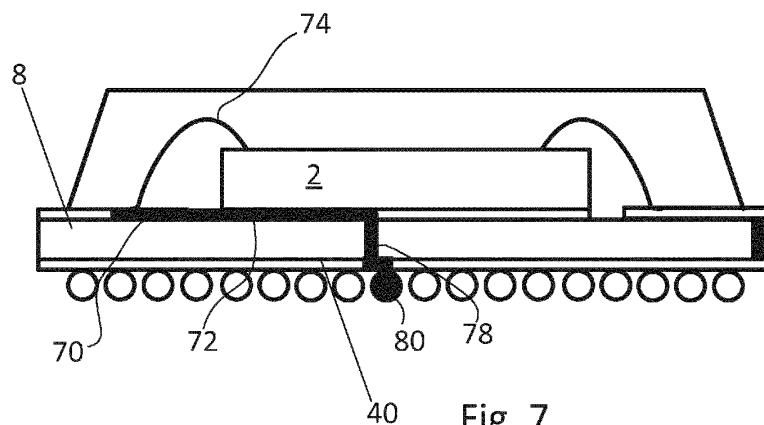


Fig. 7

(57) Abstract: The present application is directed at protecting integrated circuits which are packaged in a wire-bond ball grid array form of package and in particular is directed at preventing an attack through the substrate of the package directly underneath the integrated circuit.

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